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Presentation on Power Amplifier Design using ADS

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Power Amplifier Design using ADS



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October 12, 2004



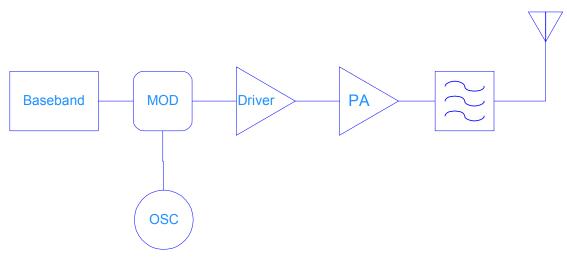
Outline

- Introduction
- DC and Loadline analysis
- Bias and Stability
- LoadPull
- Matching using Smith Chart Utility
- SourcePull
- PA Characterization Did we meet the specification?
- Optimize/Fine Tune the design
- Test Design with real world modulated signals
- Layout

Why do we need a Power Amplifier?

Power Amplifiers (PA) are in the transmitting chain of a wireless system. They are the final amplification stage before the signal is transmitted, and therefore must produce enough output power to overcome channel losses between the transmitter and the receiver.

Basic Transmitter



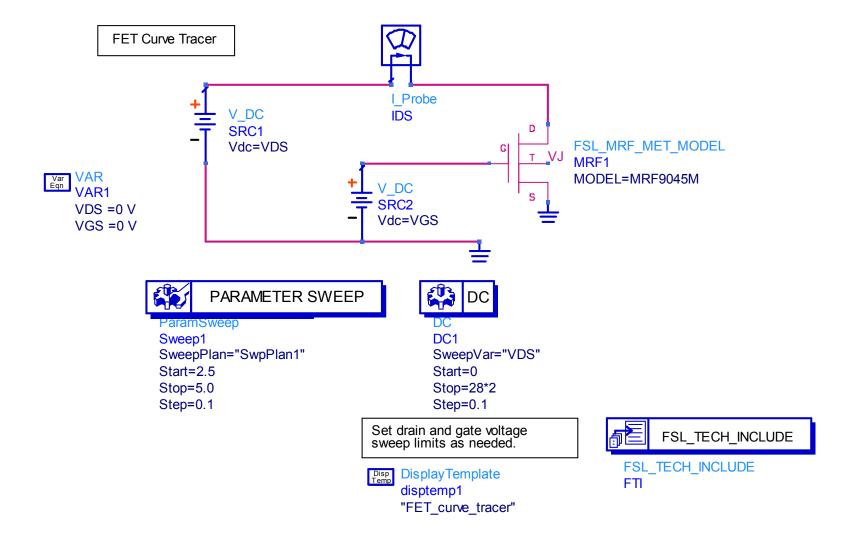
PA requirements

- The PA is typically the primary consumer of power in a transmitter. A major design requirement is how efficiently the PA can convert DC power to RF output power.
- The design engineer has to often concern himself with the Efficiency of the Power Amplifier. Notice that efficiency translates into either lower operation cost (e.g. cellular basestation) or longer battery life (e.g. wireless handheld).
- PA linearity is another important requirement, the input/output relationship must be linear to preserve the signal integrity.
- The design of PAs often involves the tradeoff of efficiency and linearity.

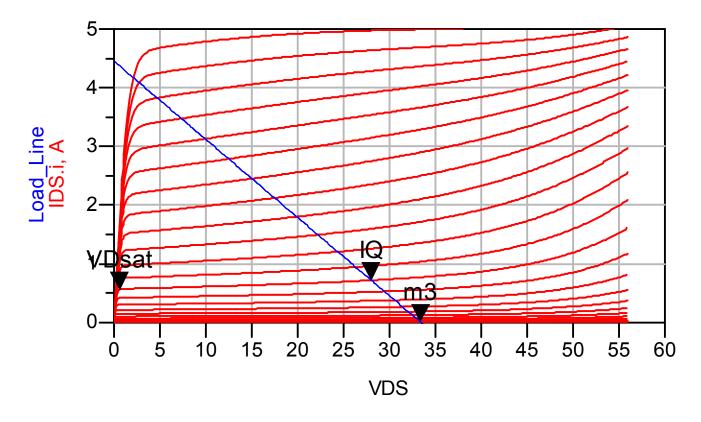
PA Design Requirement

- RF Output Power: 50 W PEP
- Input Drive Level: 1 W
- Output Load (RL): 50 Ω
- Efficiency $(\eta) > 50\%$
- Bias Voltage: 28 V
- Device: MRF9045M

DC Curves



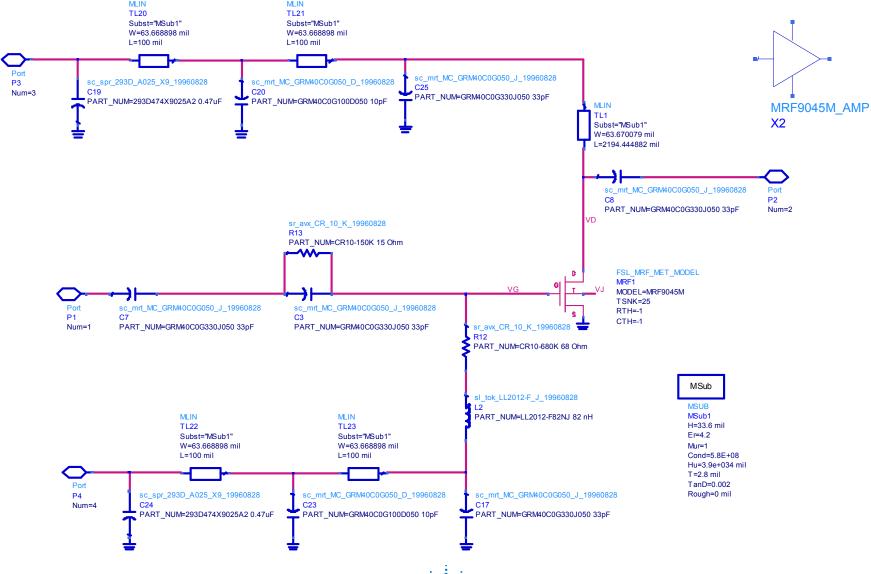
DC Curves



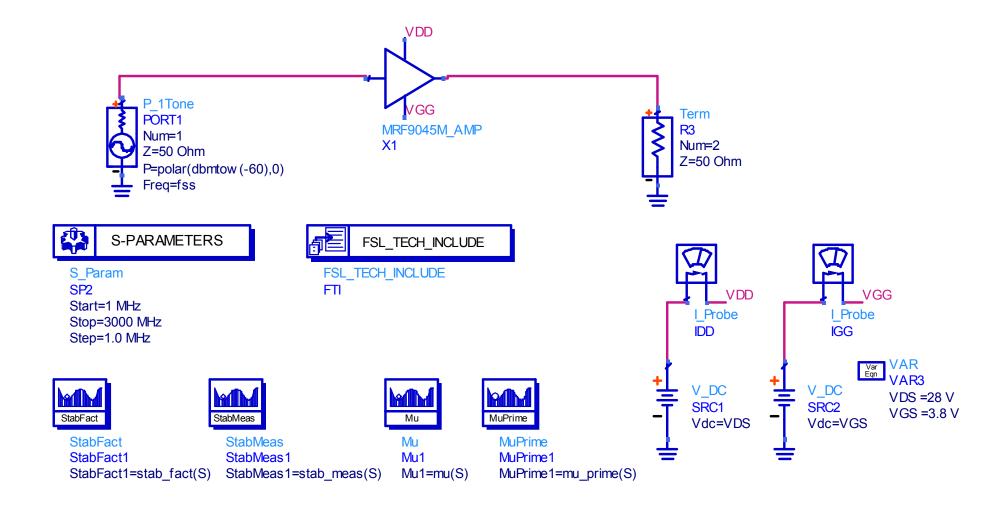
VDsat VDS=0.600 IDS.i=0.562 VGS=3.800000 IQ VDS=28.000 IDS.i=0.717 VGS=3.800000 m3 VDS=33.400 IDS.i=0.004 VGS=2.500000



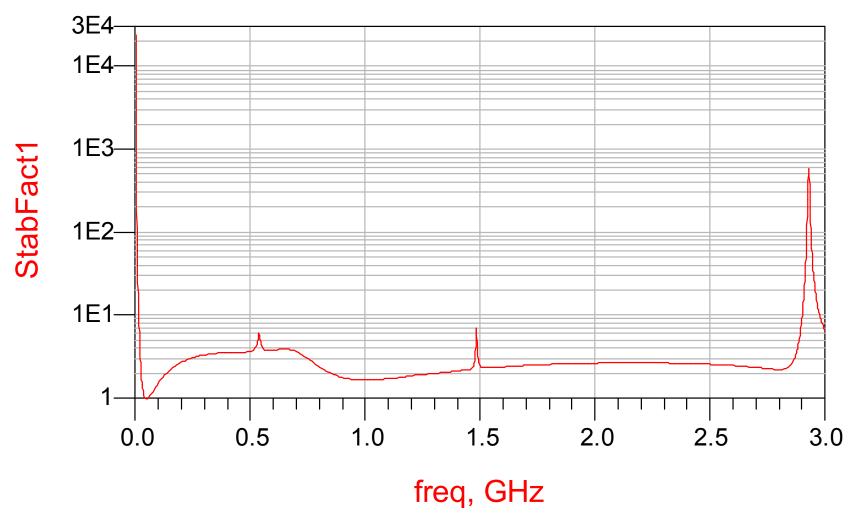
Bias and Stability



Stability Analysis



Stability Analysis



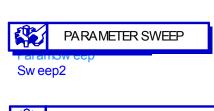


Impedance Matching

- The need for matching circuits is because amplifiers, in order to perform in a certain way(e.g. maximize output power), must be presented with a certain impedance at both the load and the source ports.
- For example in order to deliver maximum power to the load R_L the transistor must have termination Z_s and Z_L .
- The input matching network is designed to transform the generator impedance $R_{\rm s}$ to the optimum source impedance $Z_{\rm s}$.
- The output matching network transform the load termination R_L (50 Ω) to the optimum load impedance Z_L .
- A LoadPull measurement will help the designer determine the optimum load impedance Z_L.



LoadPull Setup



HARMONIC Harmonic Balance

HARMONIC BALANCE

HB1
Freq[1]=RFfreq
Order[1]=15

Set Load and Source impedances at harmonic frequencies

VAR VAR2

 $Z_1_2 = Z_0 + j*_0$ $Z_1_3 = Z_0 + j*_0$

 $Z \mid 4 = Z0 + j*0$

 $Z \mid 5 = Z0 + i*0$

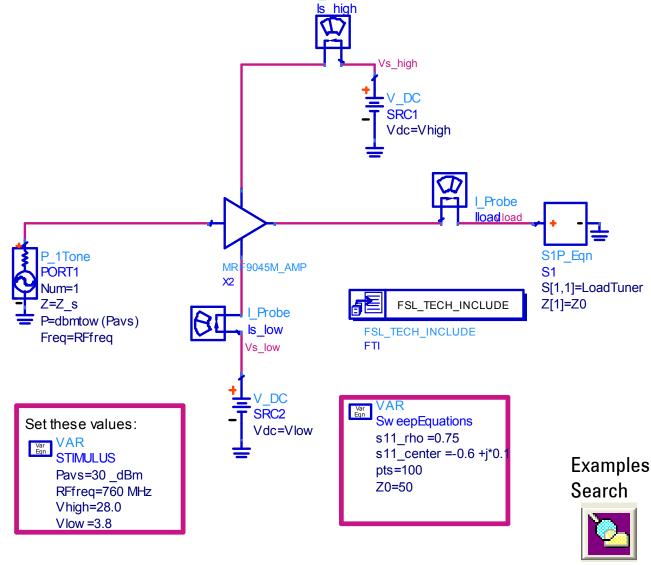
Z = 1.0 + j*0

 $Z_s^2 = Z_0 + j*0$

 $Z_s_3 = Z_0 + j*_0$

 $Z_s_4 = Z_0 + j*0$

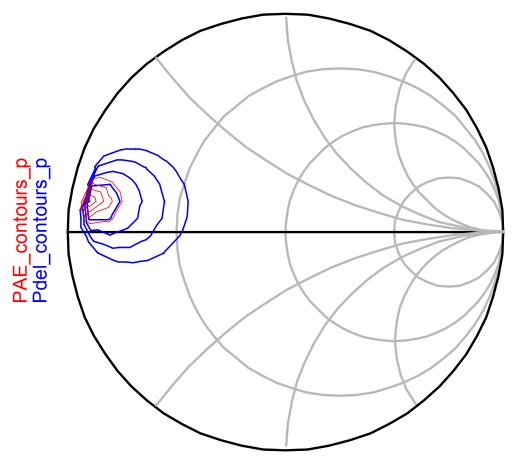
 $Z_s_5 = Z_0 + j*0$



I Probe



LoadPull Contours



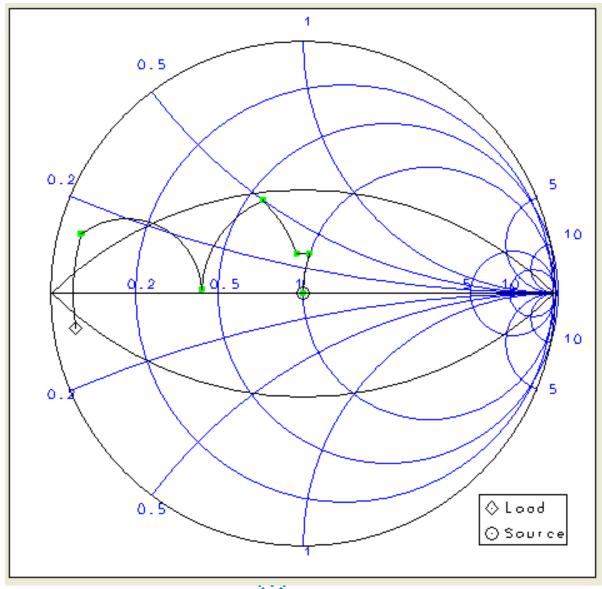
m2 indep(m2)=6 Pdel_contours_p=0.914 / 171.170 level=44.195857, number=1 impedance = 2.265 + j3.852

m1 indep(m1)=6 PAE_contours_p=0.914 / 171.180 level=47.552308, number=1 impedance = 2.265 + j3.848

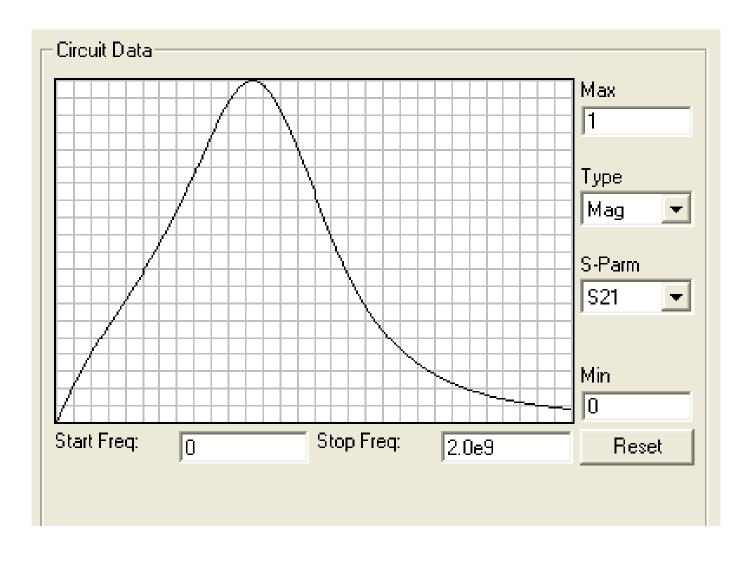
indep(Pdel_contours_p) (0.000 to 46.000) indep(PAE_contours_p) (0.000 to 18.000)



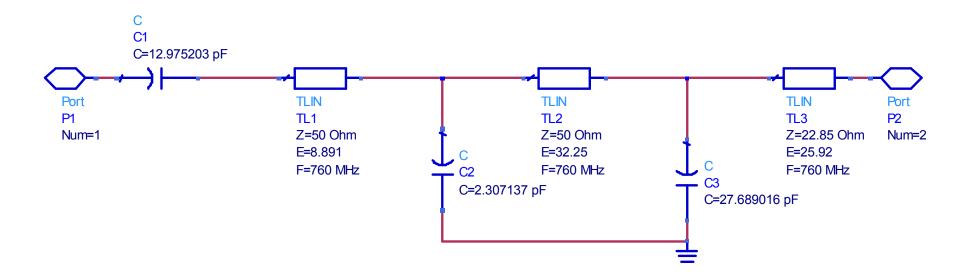
Matching using Smith Chart Utility



Matching using Smith Chart Utility



Output Match





DA_SmithChartMatch1_output_match_design

DA_SmithChartMatch1

F=760 MHz

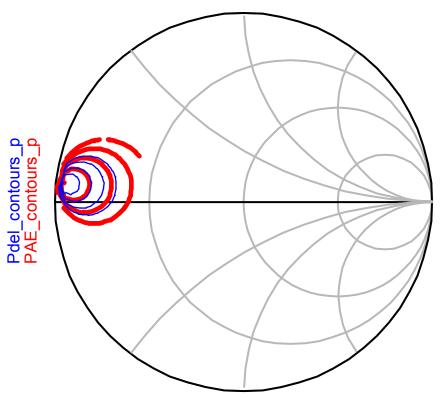
Zs=50 Ohm

ZI=(2.300-j*3.800) Ohm

Z0=50 Ohm



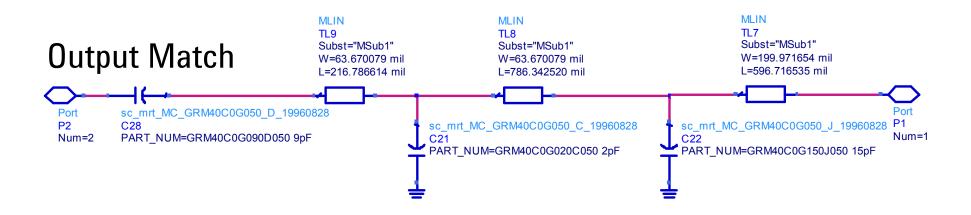
SourcePull Contours

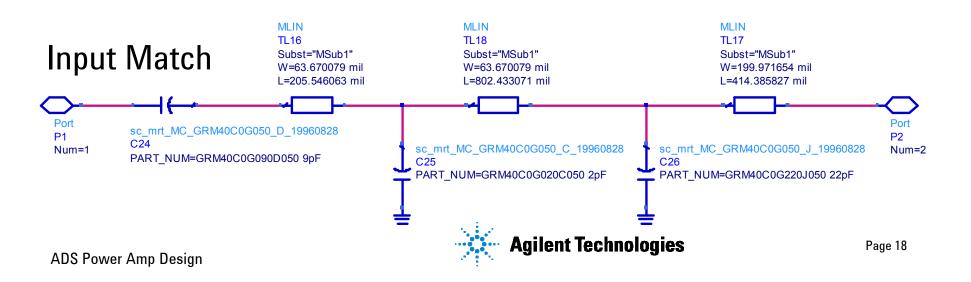


m2 indep(m2)=4 Pdel_contours_p=0.960 / 174.023 level=46.038749, number=1 impedance = 1.016 + j2.609

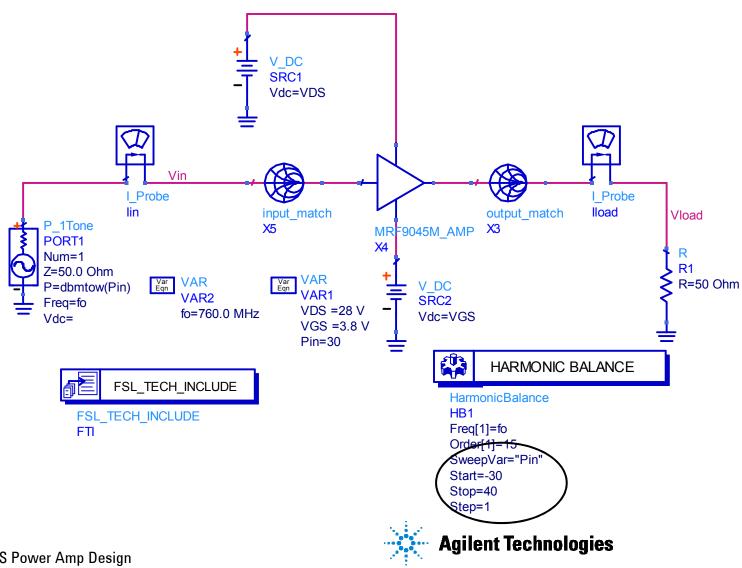
m1 indep(m1)=4 PAE_contours_p=-0.952 + j0.100 level=58.130703, number=1 impedance = 1.096 + j2.618

Matching Circuits

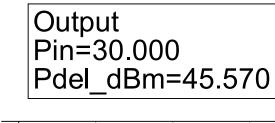


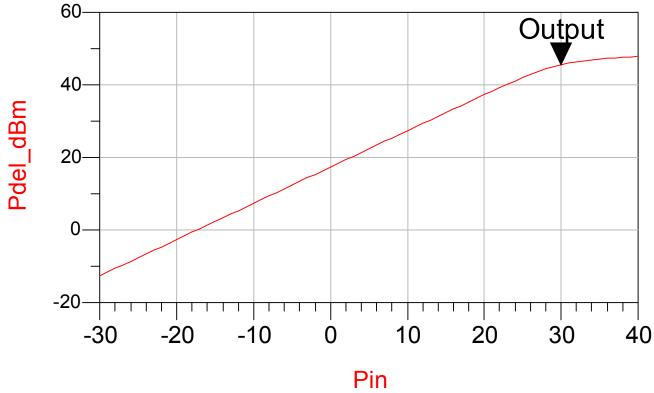


Complete Design Power Sweep

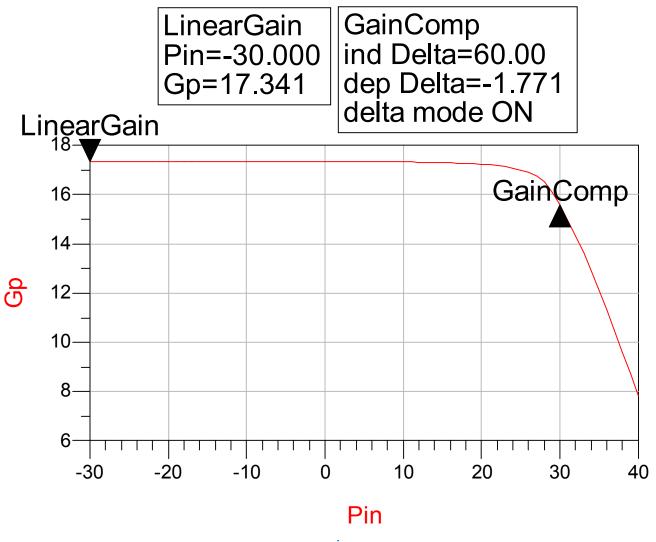


Power Compression Curve

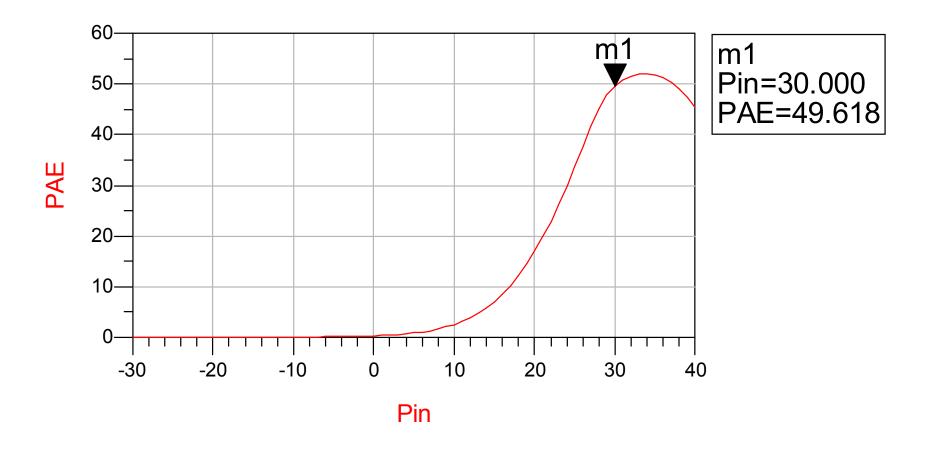




Gain Compression Curve



Power Added Efficiency

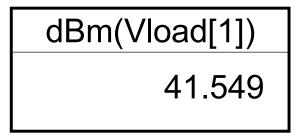


Getting ready to Optimize the PA

- The next step is to optimize the design to meet the requirements.
- The Designer can take the opportunity to see if other requirements, such as layout will require any changes before proceeding to optimize.
- Example: we notice that the transistor pads are rather wide and the Tlines leading up to it are not the same width.
- Since the Tlines are much narrower, we could add a taper so we have a nice transition.
- We included a MTAPER at the input and output side

MTAPER
Taper2
Subst="MSub1"
W1=199.971654 mi
W2=63.670079 mil
L=100.0 mil







Optimization Setup



Optim1

OptimType=Gradient

MaxIters=25

DesiredError=0.0

FinalAnalysis="None"

NormalizeGoals=no

SetBestValues=yes

SaveSolns=yes

SaveGoals=yes

SaveOptimVars=no

UpdateDataset=yes

SaveNominal=no

SaveAllIterations=no

UseAllOptVars=yes

UseAllGoals=yes

SaveCurrentEF=no

GOAL

GOAL

Goal

Goal Goal 2

Expr="dBm(Vload[1])" Expr="dBm(Vload[2])-dBm(Vload[1])"

Goal

SimInstanceName="HB1" SimInstanceName="HB1"

Min=47.0 Min=

Max= Max=-40 Weight=

RangeVar[1]= RangeVar[1]=

RangeMin[1]= RangeMin[1]=

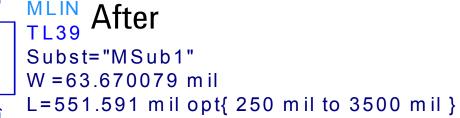
RangeMax[1]= RangeMax[1]=

Optimization Results

InitialEF	FinalEF	
67.187	0.000	

optlter	Goal1	Goal2
10	47.003	-40.017





Optimization Values

TL39.L*1e5/2.54

551.591

TL15.L*1e5/2.54

247.144

TL7.L*1e5/2.54

320.449

TL30.L*1e5/2.54

814.900

TL8.L*1e5/2.54

622.341

TL31.L*1e5/2.54

202.643

TL9.L*1e5/2.54

248.635

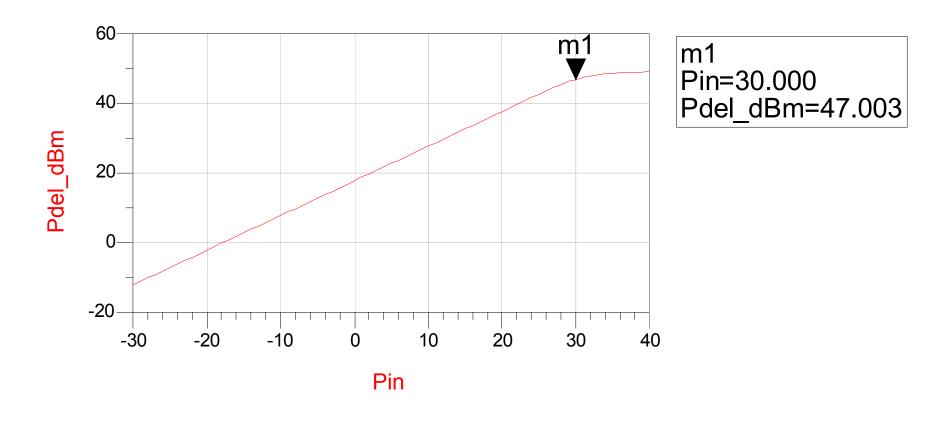
TL32.L*1e5/2.54

184.709

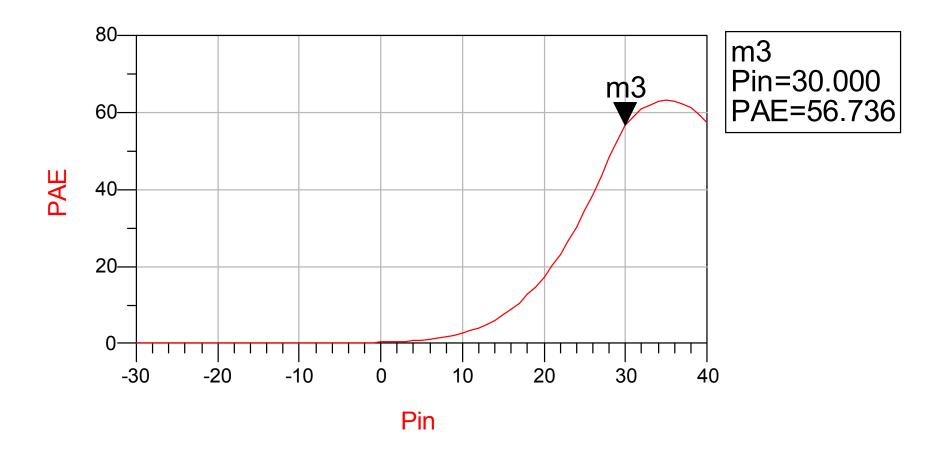
TL10.L*1e5/2.54

244.711

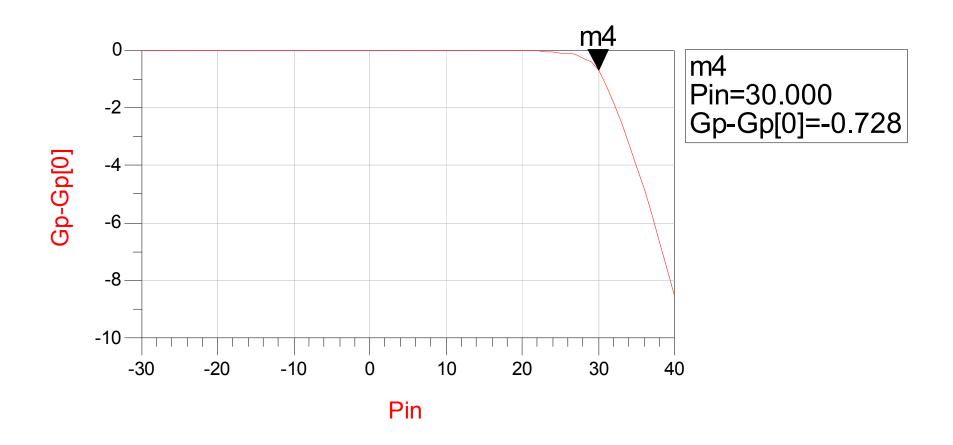
PA Results



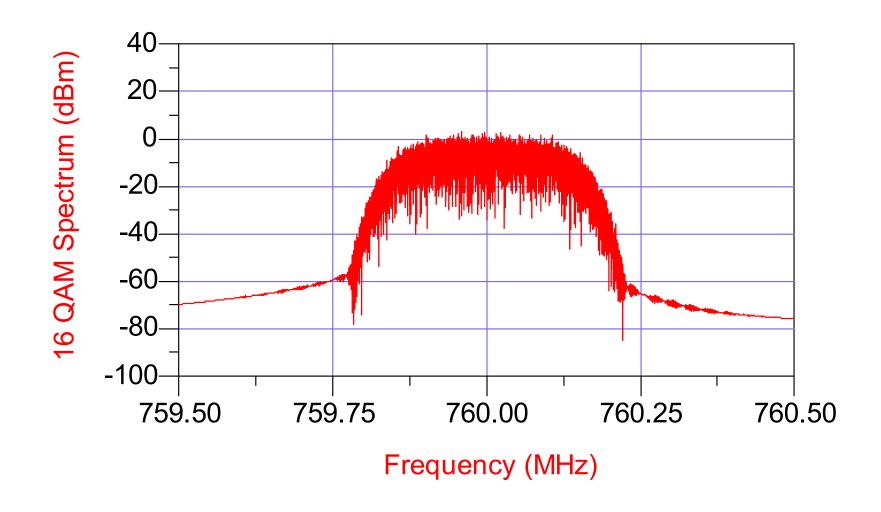
Power Added Efficiency



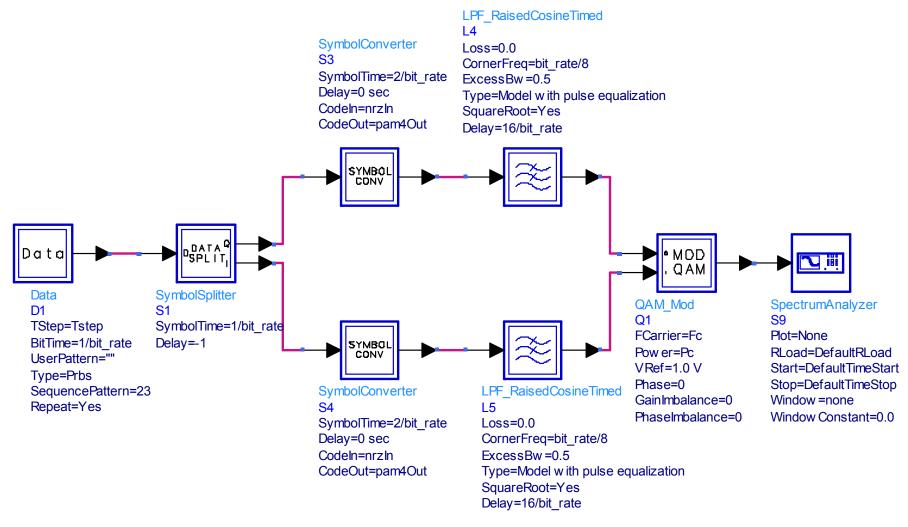
Gain Compression Curve



Complex Modulated Signal



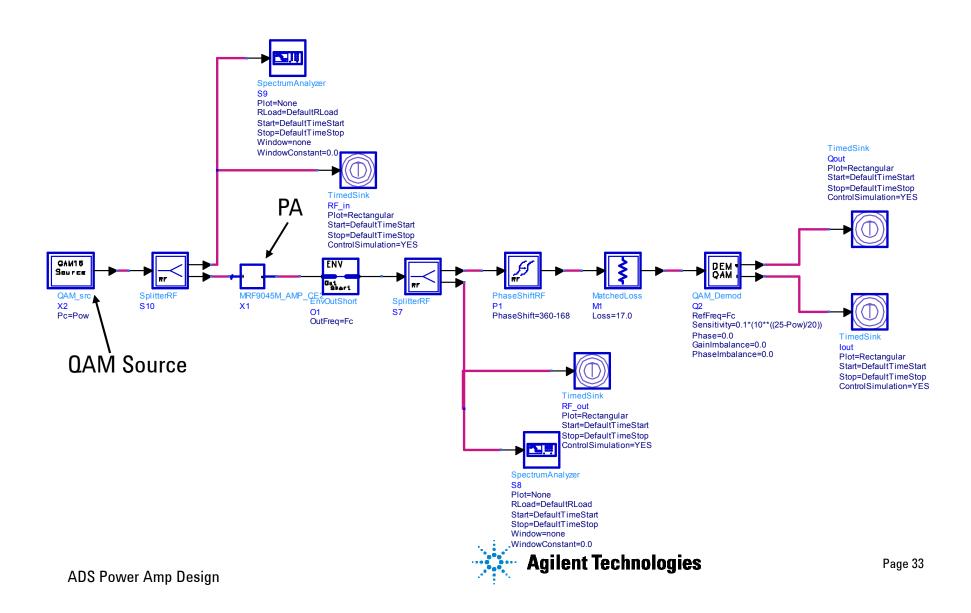
16 QAM Modulated Source



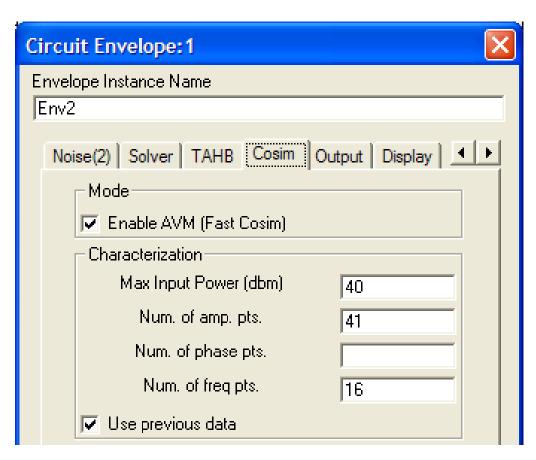
DSP and Analog Circuits Setup

- Create a subcircuit with your analog design.
- You need to add either Circuit Envelope or Transient controller to the analog circuit.
- We use Circuit Envelope specifically with our PA since we have a Modulated Carrier.
- Circuit Envelope will also allow the use of Fast Cosim (Automatic Verification Modeling – AVM). This will dramatically increase the simulation speed.
- In the DSP schematic we will create the Modulated Carrier, feed it to the PA and collect the signal samples and spectrum.
- The DSP schematic contains a Envelope Output Selector component used for interfacing between circuit subnetwork output and the signal processing components.

Ptolemy Cosim Schematic



Fast Cosim Improvements



Simulation Time Benchmark:

Total bits: 1024 bits

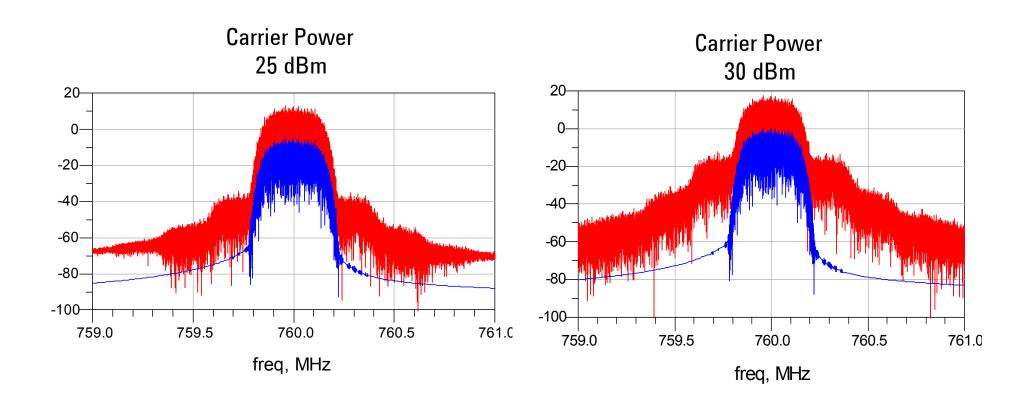
AVM disabled: 410 sec

AVM enabled: 13 sec

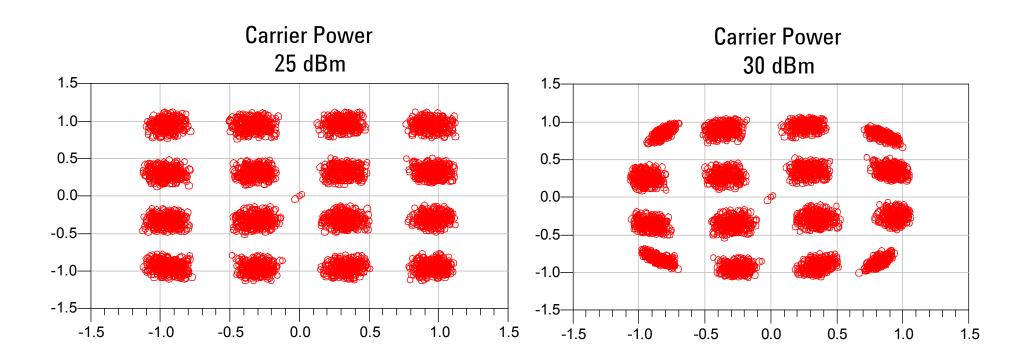
AVM data reuse: 5.5 sec

AVM data reuse (16 Kbits): 17.5 sec

Cosimulation Results - Spectrum



Cosimulation Results - Constellation



Cosimulation Results

Carrier Power 30 dBm

peakP_in	eakP_in peak_avg_in avgP	
32.163	4.951	27.212

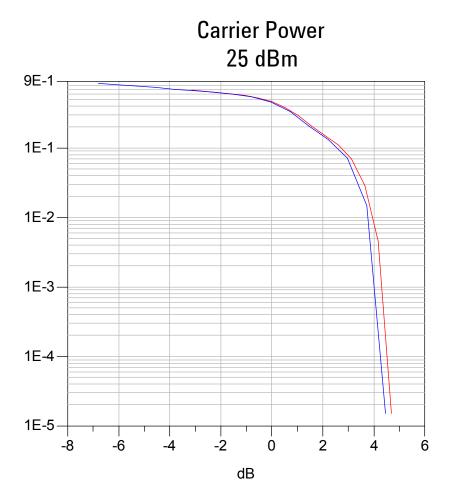
peakP_out	peak_avg_out	avgPout
47.969	3.516	44.453

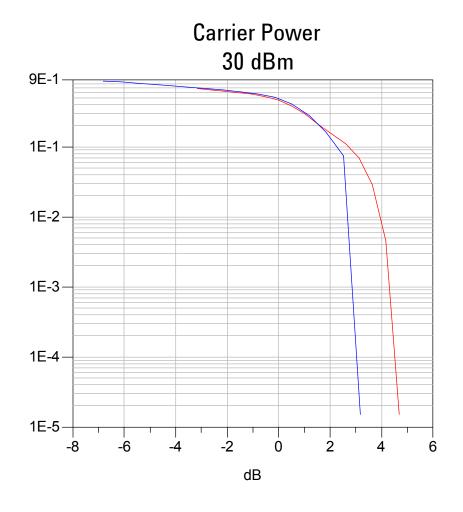
Carrier Power 25 dBm

peakP_in	peak_avg_in	avgPin
30.000	7.788	22.212

peakP_out	peak_avg_out	avgPout
44.715	4.832	39.883

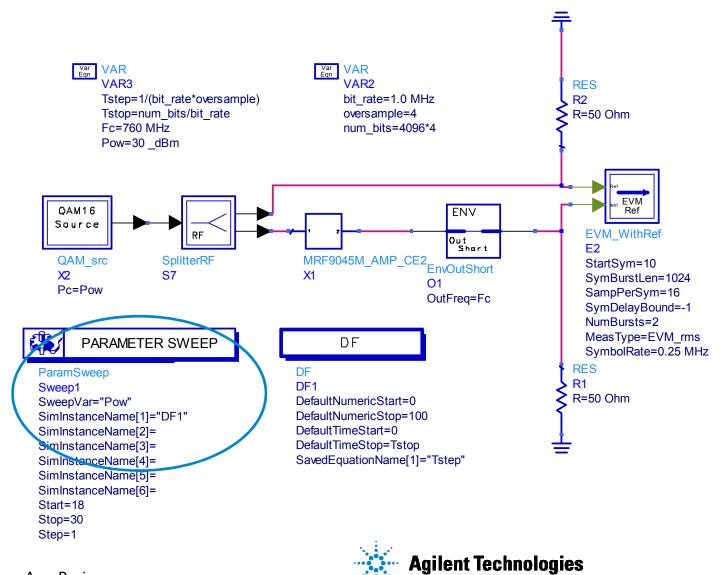
Cosimulation Results – CCDF





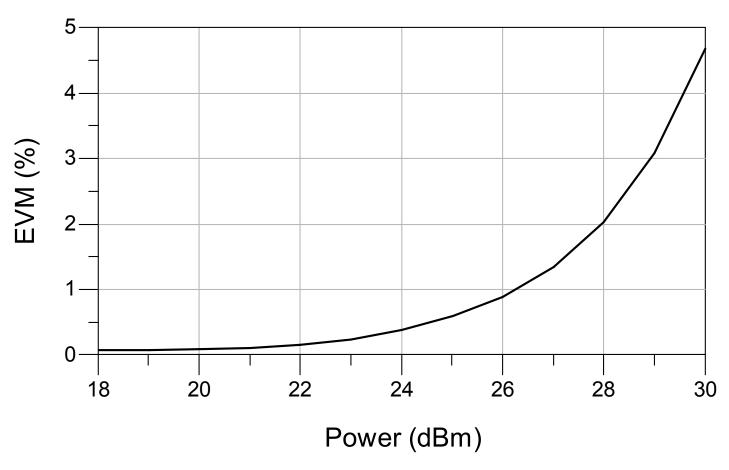


EVM vs. Power Measurement

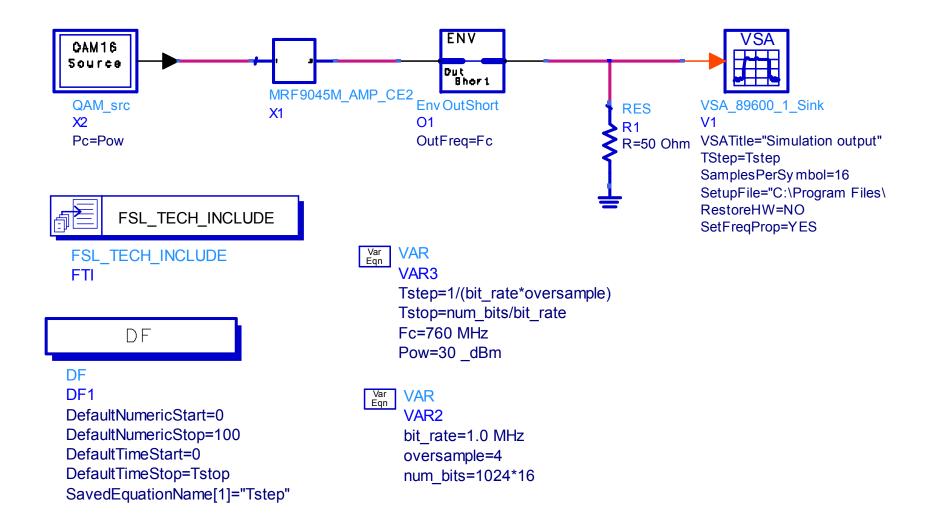


EVM vs. Power Results

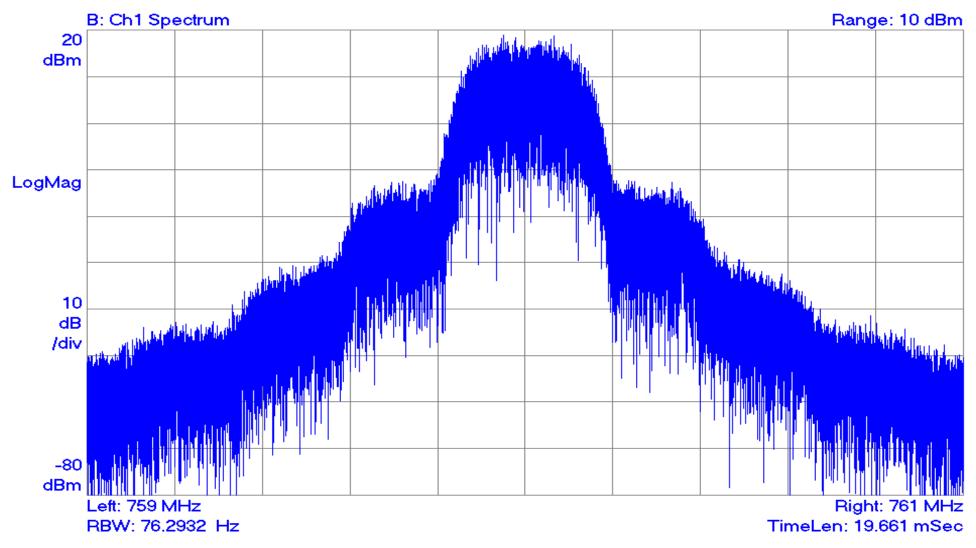




ADS to VSA link

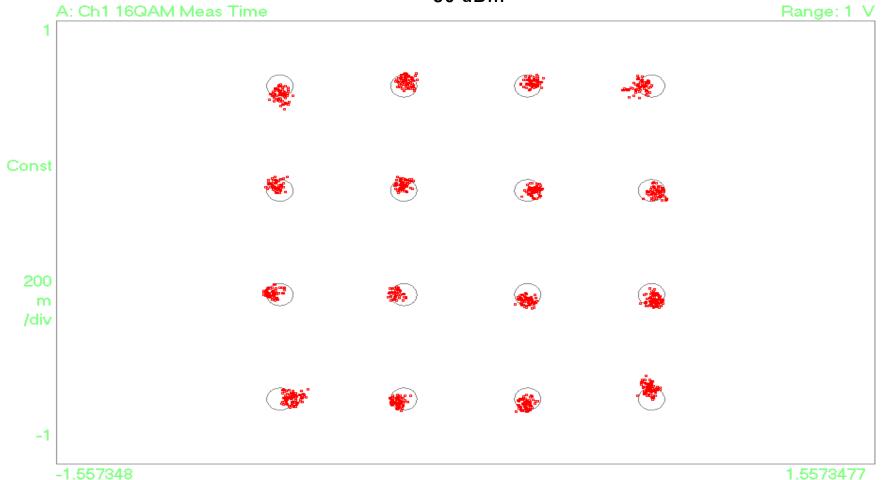


VSA Spectrum from ADS Cosim



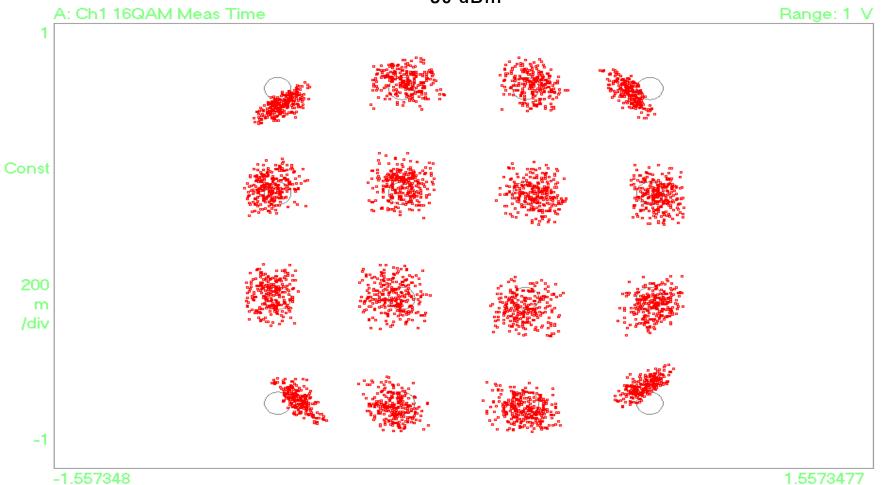
VSA Constellation from ADS Cosim

Carrier Power 30 dBm



VSA Constellation from ADS Cosim

Carrier Power 30 dBm

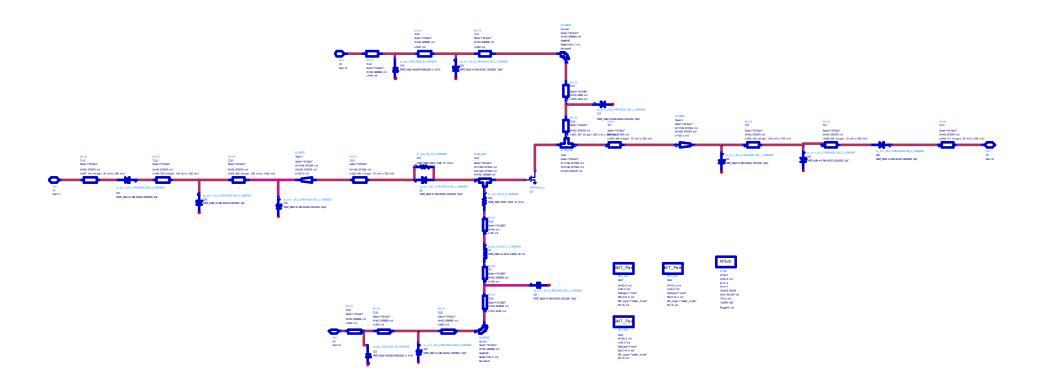


VSA EVM from ADS Cosim

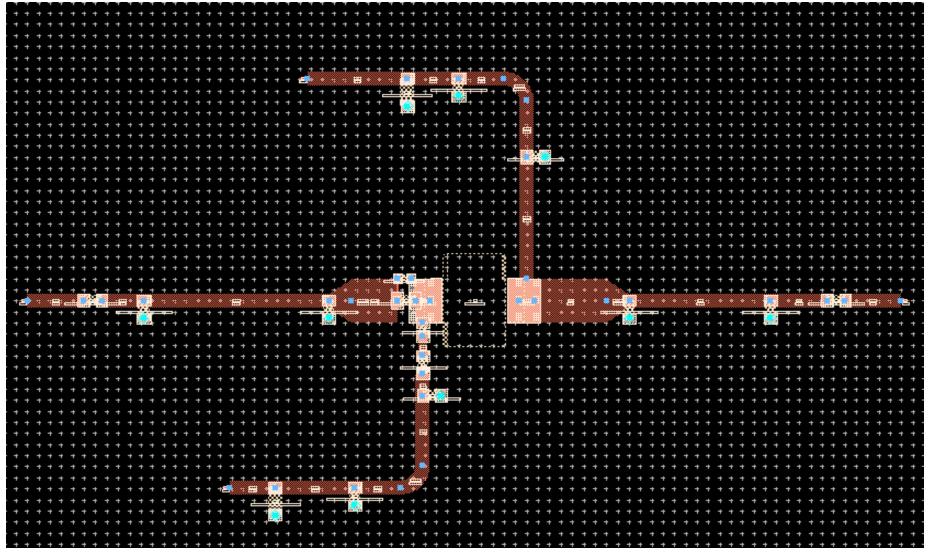
Carrier Power 30 dBm

	D: Ch1 10	QAM Sym	s/Errs		Tir	me:27	
EVM	= 4.1676	%rms	12.719	% pk at	sym	1468	
Mag Err	= 3.1291	%rms	-11.221	% pk at	sym	2507	
Phase Err	= 2.6647	deg	-11.881	deg pk at	sym	3471	
Freq Err	= 5.1206	mHz					
IQ Offset	= -65.85	dB	SNR(ME	R) = 25.051		dB	
Quad Err	= 94.065	mdeg	Gain Imb	0.01		dB	

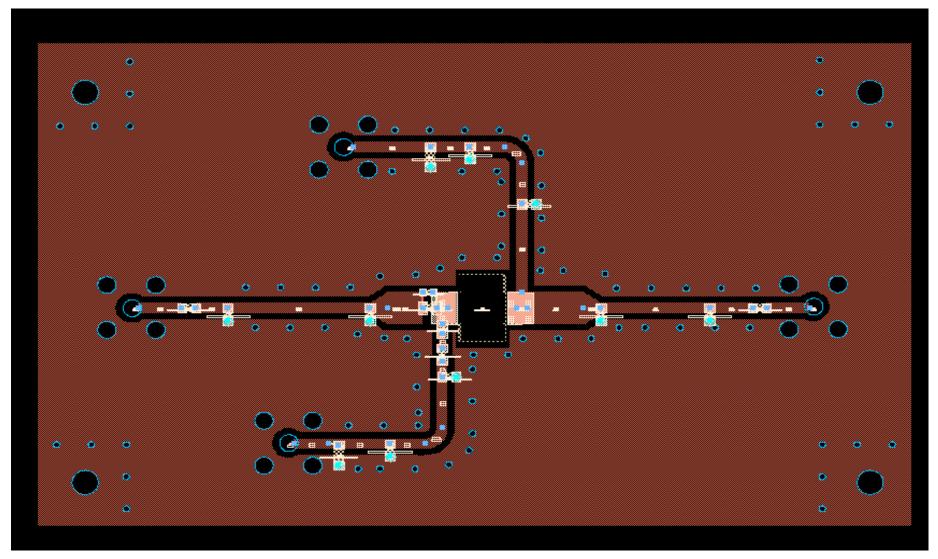
PA Layout



PA Layout – Generated from Schematic



PA Layout – Ground Fill



Other Possibilities

- Run an EM Cosimulation include layout effects in the simulation.
 Optimize design if necessary.
- Run Loadpull for IP3 or ACPR. The optimum load would then be a compromise between all the requirements.
- Use Connection Manager and real PA to validate design and compare vs. simulated results.
- Create a behavioral data model that can be used to protect you IP yet give access to your design results.

If there is any topic about PA Design and ADS you wish to discuss email me: wilfredo_rivas-torres@agilent.com



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